

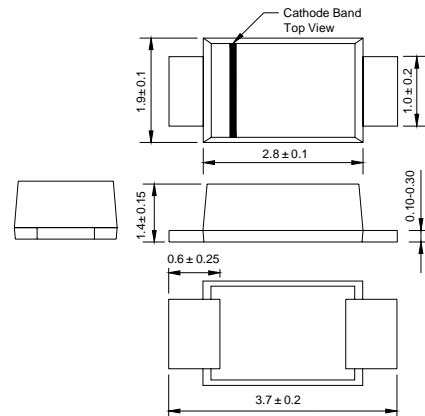
### Features

- Low profile space
- Ideal for automated placement
- Glass passivated chip junctions
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering:  
260°C/10 seconds at terminals
- Component in accordance to  
RoHS 2002/95/1 and WEEE 2002/96/EC

### Mechanical Date

- **Case:** JEDEC SOD-123FL molded plastic body over glass passivated chip
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Laser band denotes cathode end

### SOD - 123FL

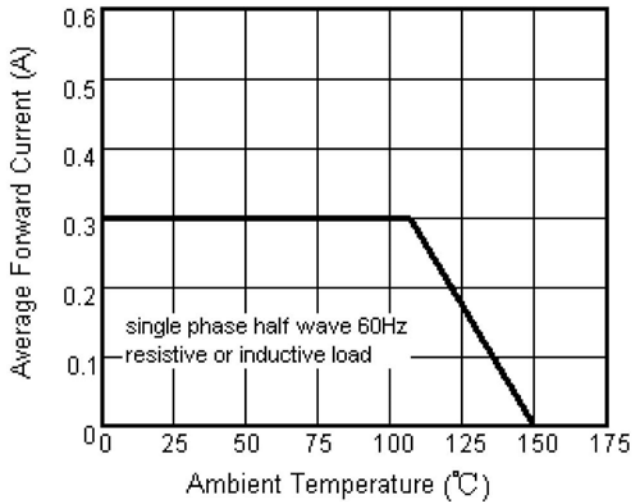
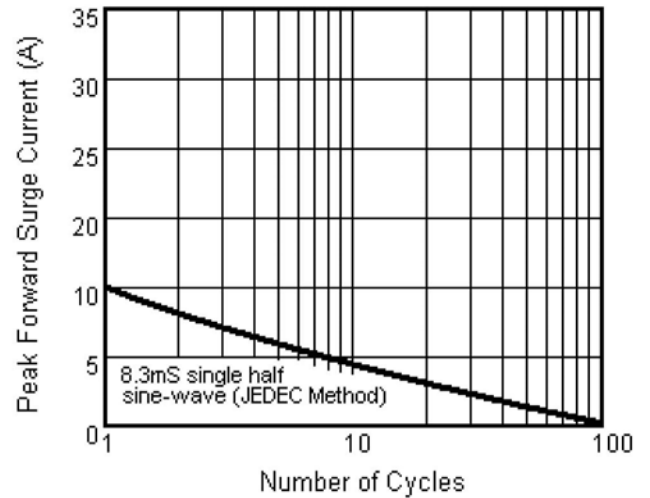
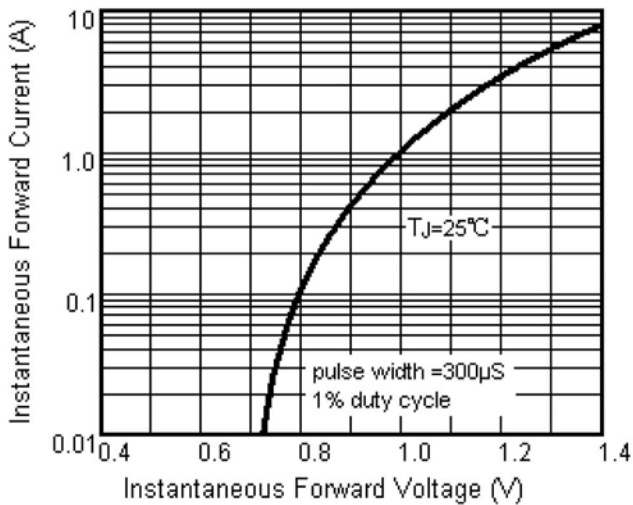
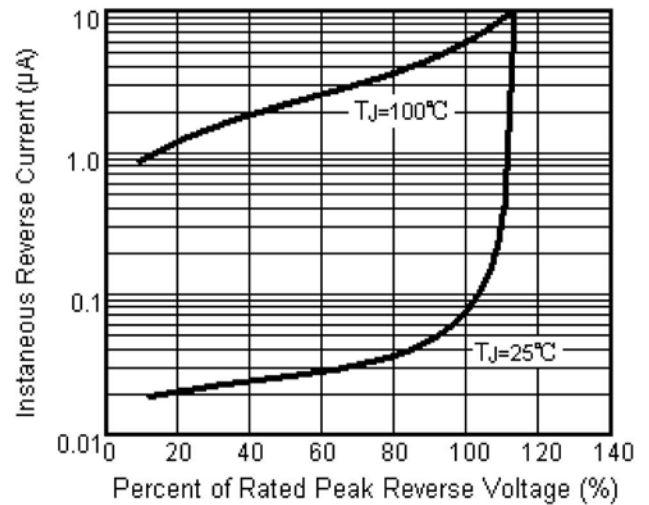


Dimensions in millimeters

### Maximum Ratings & Thermal Characteristics & Electrical Characteristics

( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)

DSR- Symbol	0.3A	0.3B	0.3D	0.3G	0.3J	0.3K	0.3M	UNIT	
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	$I_{F(AV)}$	0.3							A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	10							A
Maximum instantaneous forward voltage at 0.5A	$V_F$	1.1							V
Maximum DC reverse current $T_A = 25\text{ }^\circ\text{C}$ at Rated DC blocking voltage $T_A = 100\text{ }^\circ\text{C}$	$I_R$	5.0 50							$\mu\text{A}$
Typical junction capacitance at 4.0 V ,1MHz	$C_J$	14							pF
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$

**Characteristic Curves ( $T_A=25^\circ\text{C}$  unless otherwise noted)**
**Fig.1 Forward Current Derating Curve**

**Fig.2 Maximum Non-Repetitive Peak Forward Surge Current**

**Fig.3 Typical Instantaneous Forward Characteristics**

**Fig.4 Typical Reverse Characteristics**

**Fig.5 Typical Junction Capacitance**
